

PT480E0000F

Phototransistor



■ Features

1. Side view detection type
2. Plastic mold with resin lens
3. Narrow directivity angle
4. Transparent resin
5. Lead free and RoHS directive component

■ Agency Approvals/Compliance

1. Compliant with RoHS directive (2002/95/EC)
2. Content information about the six substances specified in “Management Methods for Control of Pollution Caused by Electronic Information Products Regulation” (popular name: China RoHS) (Chinese: 电子信息产品污染控制管理办法); refer to page 8

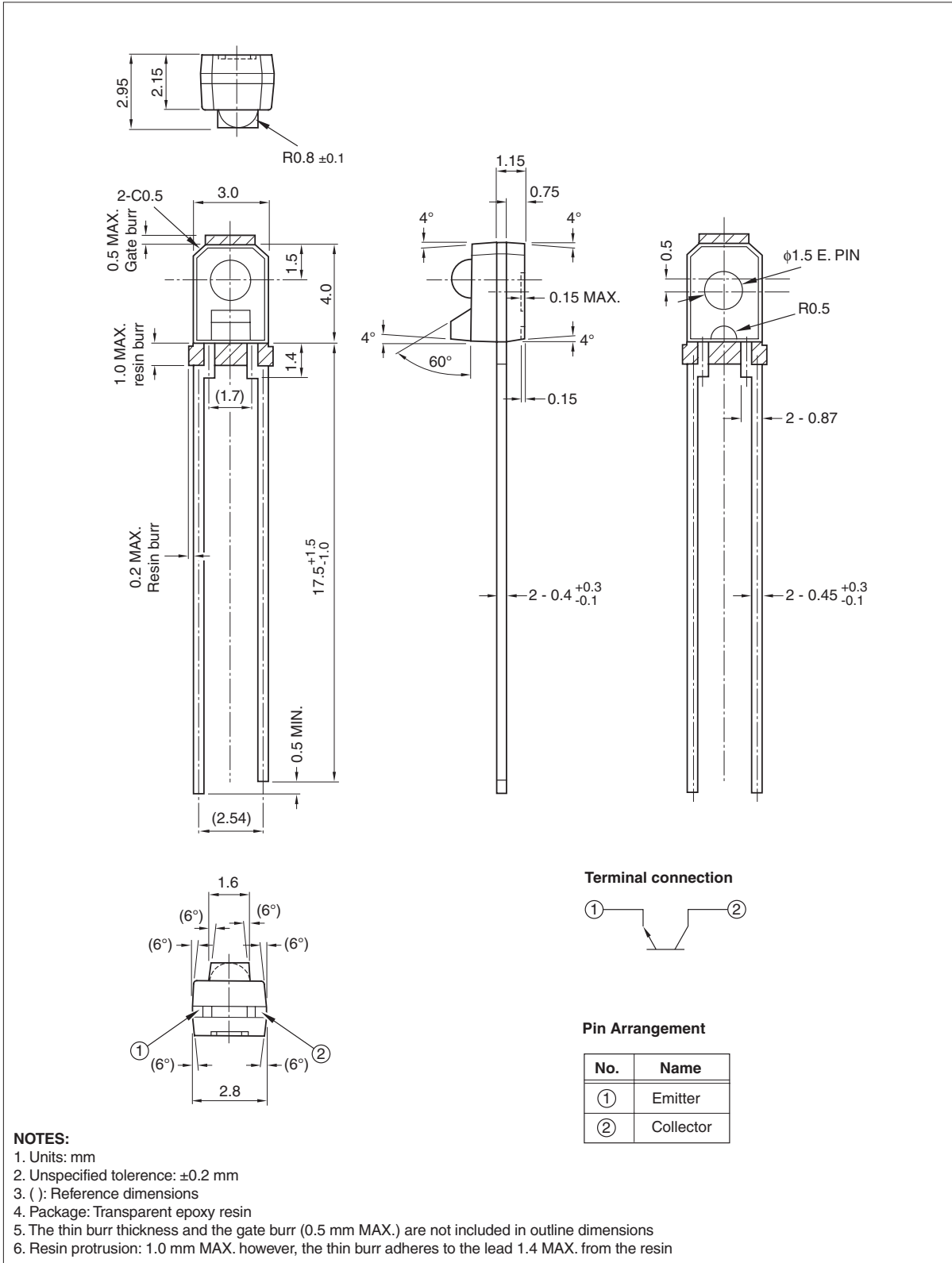
■ Applications

1. Optoelectronic switches
2. Automatic stroboscopes
3. Office automation equipment
4. Audio visual equipment
5. Home appliances
6. Telecommunication equipment
7. Measuring equipment
8. Tooling machines
9. Computers

Notice The content of data sheet is subject to change without prior notice.

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Outline Dimensions



NOTES:

- Units: mm
- Unspecified tolerance: ± 0.2 mm
- (): Reference dimensions
- Package: Transparent epoxy resin
- The thin burr thickness and the gate burr (0.5 mm MAX.) are not included in outline dimensions
- Resin protrusion: 1.0 mm MAX. however, the thin burr adheres to the lead 1.4 MAX. from the resin

■ Absolute Maximum Ratings (Ta = 25°C)

| Parameter | Symbol | Rating | Unit |
|-----------------------------|-----------|------------|------|
| Collector-emitter voltage | V_{CEO} | 35 | V |
| Emitter-collector voltage | V_{ECO} | 6 | V |
| Collector current | I_C | 20 | mA |
| Collector power dissipation | P_C | 75 | mW |
| Operating temperature | T_{opr} | -25 to +85 | °C |
| Storage temperature | T_{stg} | -40 to +85 | °C |
| Soldering temperature *1 | T_{sol} | 260 | °C |

*1 5 s (MAX.) positioned 1/4 mm from resin edge. see Figure 13

■ Electro-optical Characteristics

(Ta = 25°C)

| Parameter | Symbol | Conditions *1 | MIN. | TYP. | MAX. | Unit |
|--------------------------------------|---------------|--|------|------|------|---------------|
| Collector current | I_C | $E_e = 1 \text{ mW/cm}^2, V_{CE} = 5 \text{ V}$ | 0.4 | 1.7 | 6.0 | mA |
| Dark current | I_{CEO} | $E_e = 0, V_{CE} = 20 \text{ V}$ | – | 1.0 | 100 | nA |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $E_e = 10 \text{ mW/cm}^2, I_C = 0.5 \text{ mA}$ | – | 0.1 | 0.4 | V |
| Collector-emitter breakdown voltage | BV_{CEO} | $I_C = 0.1 \text{ mA}, E_e = 0$ | 35 | – | – | V |
| Emitter-collector breakdown voltage | BV_{ECO} | $I_E = 0.01 \text{ mA}, E_e = 0$ | 6.0 | – | – | V |
| Peak sensitivity wavelength | λ_p | – | – | 800 | – | nm |
| Response time (Rise) | t_r | $V_{CE} = 2 \text{ V}, I_C = 2 \text{ mA},$ $RL = 100 \Omega$ | – | 3.0 | – | μs |
| Response time (Fall) | t_f | | – | 3.5 | – | μs |

*1 E_e : Irradiance by CIE standard light source A (tungsten lamp)

Fig. 1 Collector Power Dissipation vs. Ambient Temperature

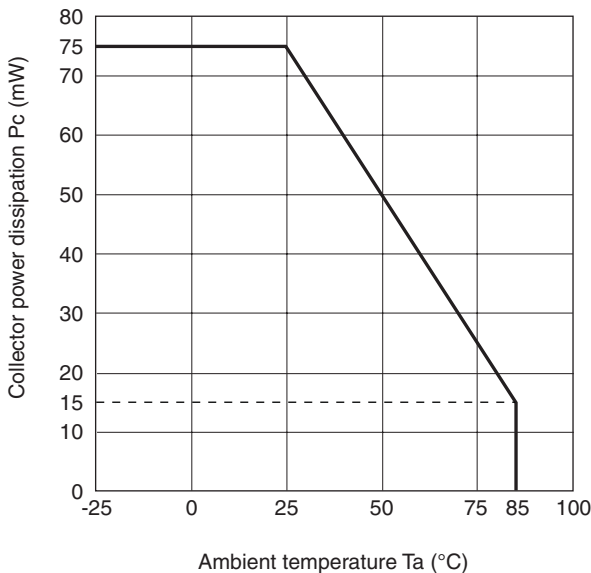


Fig. 2 Spectral Sensitivity

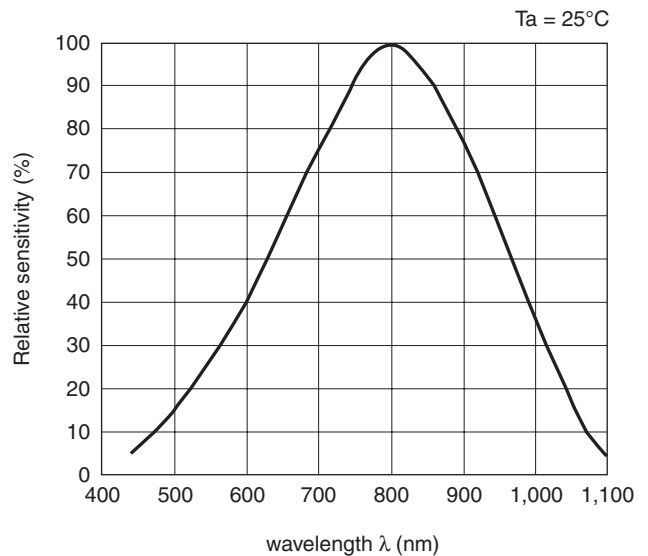


Fig. 3 Sensitivity Diagram

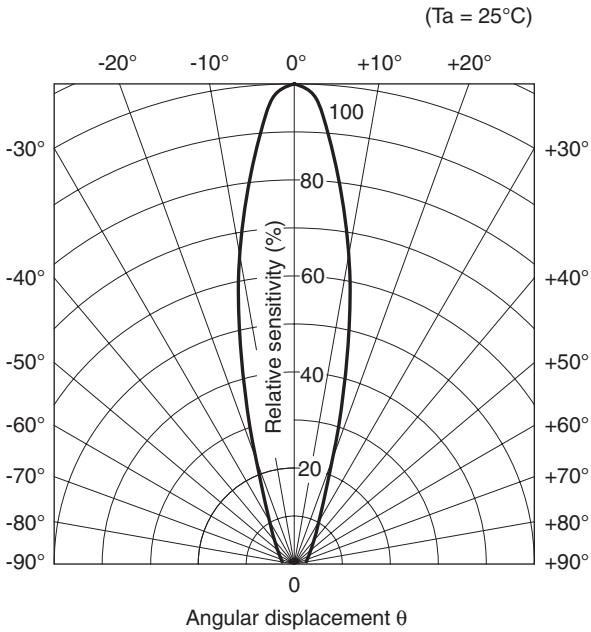


Fig. 5 Relative Collector Current vs. Ambient Temperature

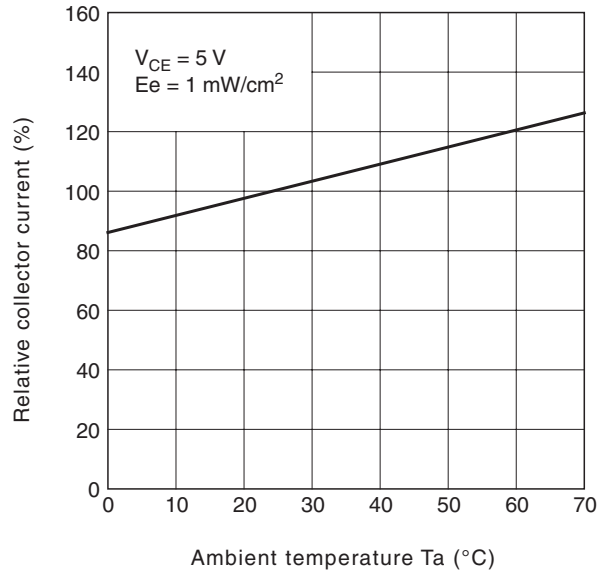


Fig. 4 Collector Dark Current vs. Ambient Temperature

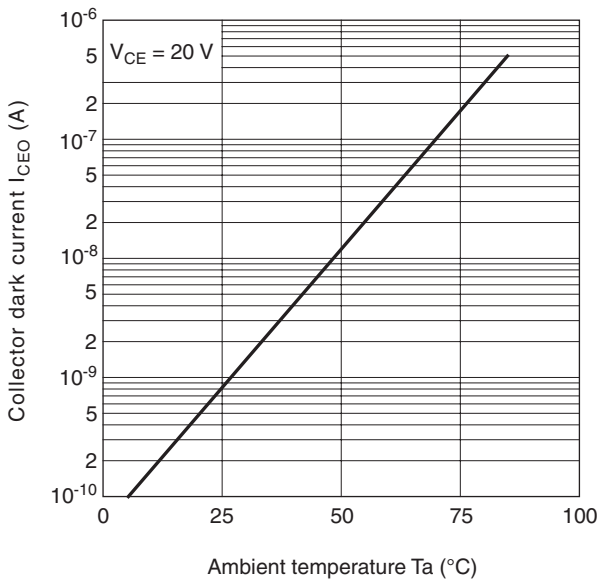


Fig. 6 Collector Current vs. Irradiance

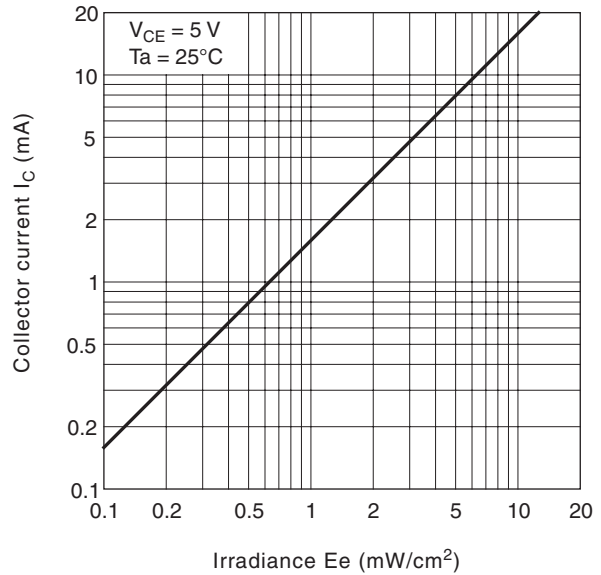


Fig. 7 Collector Current vs. Collector-Emitter Voltage

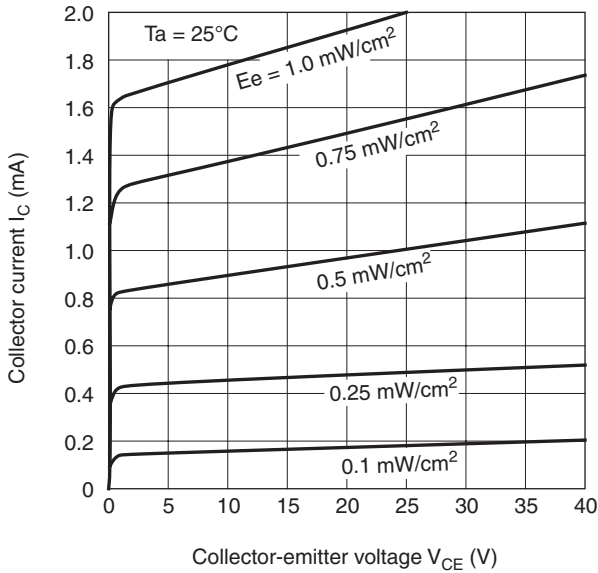


Fig. 8 Response Time vs. Load Resistance

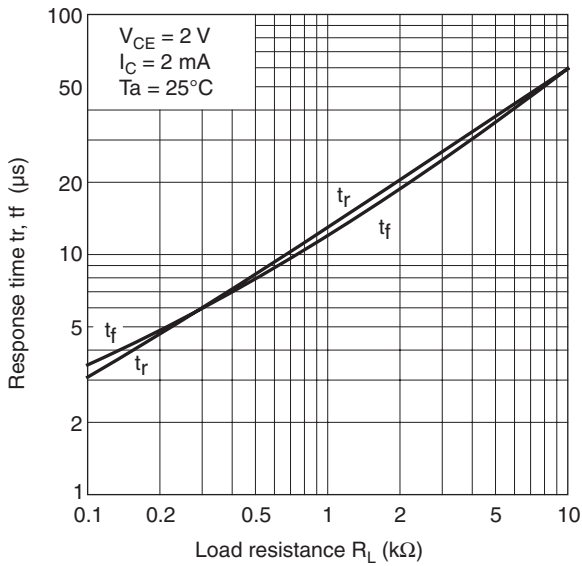


Fig. 9 Test Circuit to Determine Response Time

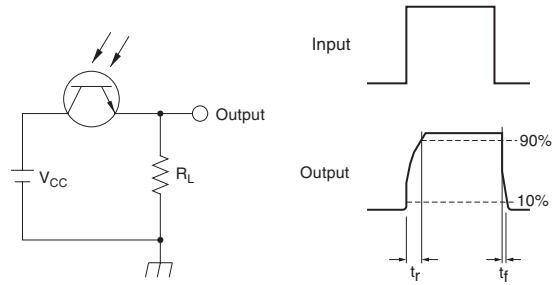


Fig. 10 Collector-to-Emitter Saturation Voltage vs. Irradiance

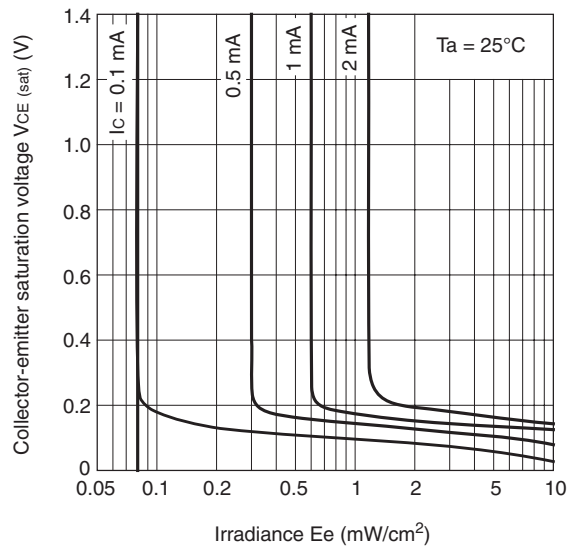
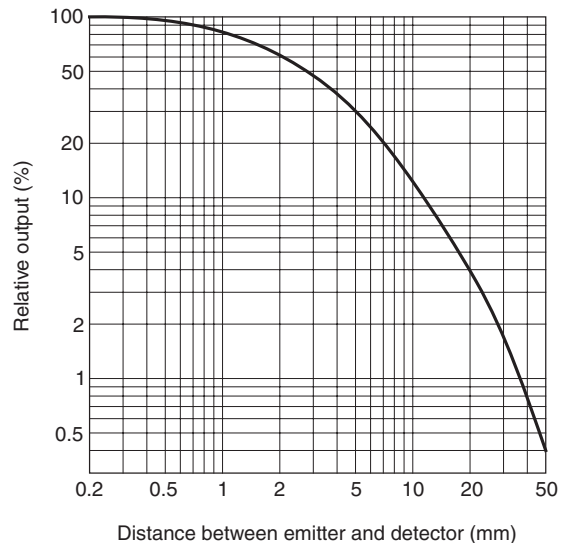
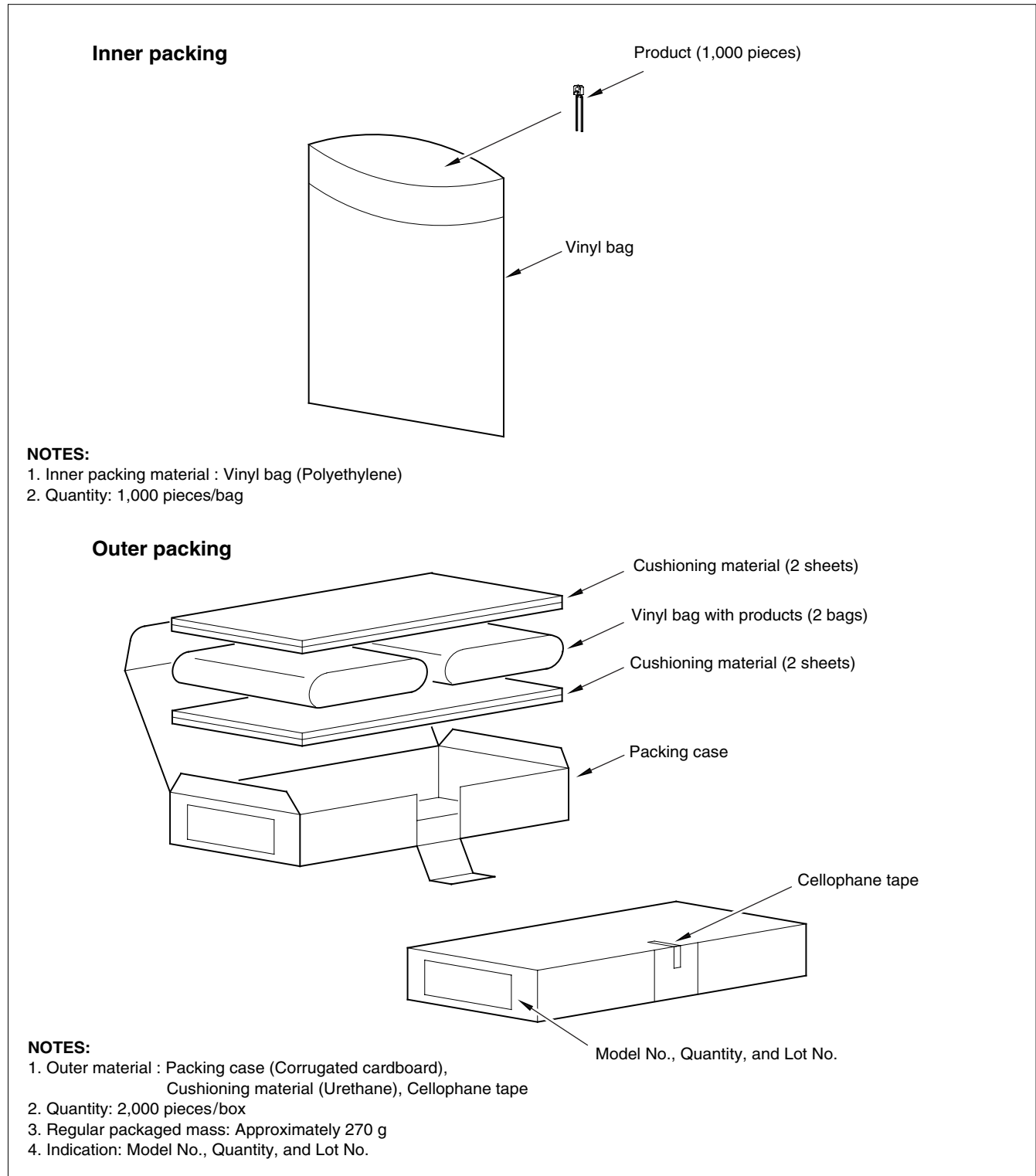


Fig. 11 Relative Output vs Distance



■ Packing Specifications

Fig. 12 Packing Method



■ Packing Specifications

1. Parts are packed in a vinyl bag, at an average quantity of 1,000 pieces per bag.
2. Bags are secured in a box as shown in illustration on page 6.
3. Product mass: 0.09 g (approx.)

■ Design Notes

1. This product is not designed to resist electromagnetic and ionized-particle radiation.

■ Manufacturing Guidelines

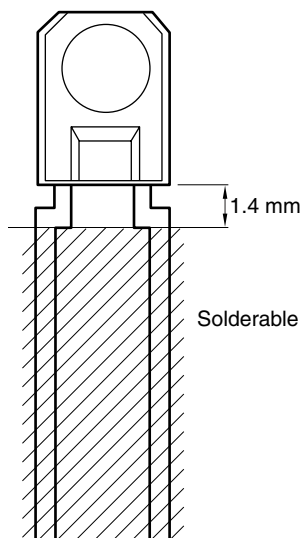
● Cleaning Instructions

1. Confirm this device's resistance to process chemicals before use, as certain process chemicals may affect the optical characteristics.
2. Solvent cleaning: Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.
3. Ultrasonic cleaning: The effect upon devices varies due to cleaning bath size, ultrasonic power output, cleaning time, PCB size and device mounting circumstances. Sharp recommends testing using actual production conditions to confirm the harmlessness of the ultrasonic cleaning methods.
4. Recommended solvent materials: Ethyl alcohol, Methyl alcohol, and Isopropyl alcohol.

● Soldering Instructions

1. Sharp recommends not soldering this part using preheat or solder reflow methods.
2. If hand soldering, use temperatures $\leq 260^{\circ}$ for ≤ 5 seconds.
3. When mounting this device, care should be taken to prevent any boundary exfoliation (pad lifting) between the solder, the pad, and the circuit board.
4. Do not subject the package to excessive mechanical force during soldering as it may cause deformation or defects in plated connections. Internal connections may be severed due to mechanical force placed on the package due to the PCB flexing during the soldering process.

Fig. 13 Soldering Area



■ Presence of ODCs (RoHS Compliance)

This product shall not contain the following materials, and they are not used in the production process for this product:

- Regulated substances: CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform). Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
- Content information about the six substances specified in “Management Methods for Control of Pollution Caused by Electronic Information Products Regulation” (Chinese: 电子信息产品污染控制管理办法)

| Category | Toxic and Hazardous Substances | | | | | |
|-------------------------|--------------------------------|--------------|--------------|---|--------------------------------|---------------------------------------|
| | Lead (Pb) | mercury (Hg) | Cadmium (Cd) | Hexavalent chromium (Cr ⁶⁺) | Polybrominated biphenyls (PBB) | Polybrominated diphenyl ethers (PBDE) |
| Infrared Emitting Diode | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ |

NOTE: ✓ indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

■ Important Notices

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- Personal computers
- Office automation equipment
- Telecommunication equipment (terminal)
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- Space applications
- Telecommunication equipment (trunk lines)
- Nuclear power control equipment
- Medical and other life support equipment (e.g. scuba)

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